

General Description

The MY50N06U is the high cell density trench N-CH MOSFETs, which provide excellent $R_{DS(ON)}$ and gate charge for most of the synchronous buck converter applications.

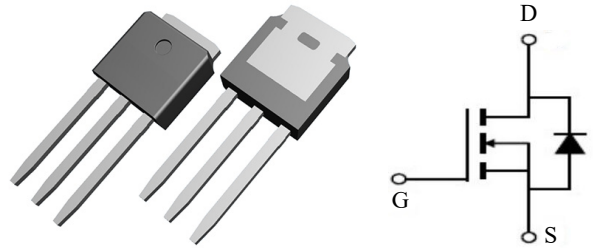


Features

V_{DSS}	60	V
I_D	50	A
$R_{DS(ON)}(at V_{GS}=10V)$	10	m Ω
$R_{DS(ON)}(at V_{GS}=4.5V)$	12	m Ω

Application

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY50N06U	TO-251	50N06U	1000

Absolute Maximum Ratings ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^{\circ}\text{C}$	Continuous Drain Current, V_{GS} @ 10V ¹	50	A
$I_D@T_C=100^{\circ}\text{C}$	Continuous Drain Current, V_{GS} @ 10V ¹	25	A
I_{DM}	Pulsed Drain Current ²	90	A
EAS	Single Pulse Avalanche Energy ³	39.2	mJ
I_{AS}	Avalanche Current	28	A
$P_D@T_C=25^{\circ}\text{C}$	Total Power Dissipation ⁴	45	W
$P_D@T_A=25^{\circ}\text{C}$	Total Power Dissipation ⁴	2	W
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}\text{C}$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	62	$^{\circ}\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	2.8	$^{\circ}\text{C/W}$

Electrical Characteristics at $T_J=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.057	---	$V/^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=20A$	---	10	14	$m\Omega$
		$V_{GS}=4.5V, I_D=10A$	---	12	15	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	---	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5.68	---	$mV/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=48V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=48V, V_{GS}=0V, T_J=55^\circ\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=5V, I_D=15A$	---	45	---	S
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	1.7	---	Ω
Q_g	Total Gate Charge (4.5V)	$V_{DS}=48V, V_{GS}=4.5V, I_D=15A$	---	19.3	---	nC
Q_{gs}	Gate-Source Charge		---	7.1	---	
Q_{gd}	Gate-Drain Charge		---	7.6	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=30V, V_{GS}=10V, R_G=3.3, I_D=15A$	---	7.2	---	ns
T_r	Rise Time		---	50	---	
$T_{d(off)}$	Turn-Off Delay Time		---	36.4	---	
T_f	Fall Time		---	7.6	---	
C_{iss}	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	---	2423	---	pF
C_{oss}	Output Capacitance		---	145	---	
C_{rss}	Reverse Transfer Capacitance		---	97	---	
I_S	Continuous Source Current ^{1,5}	$V_G=V_D=0V, \text{Force Current}$	---	---	35	A
I_{SM}	Pulsed Source Current ^{2,5}		---	---	80	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=A, T_J=25^\circ\text{C}$	---	---	1	V
t_{rr}	Reverse Recovery Time	$I_F=15A, dI/dt=100A/\mu s, T_J=25^\circ\text{C}$	---	16.3	---	nS
Q_{rr}	Reverse Recovery Charge		---	11	---	nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=28A$
4. The power dissipation is limited by 150°C junction temperature 5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation

Typical Performance Characteristics

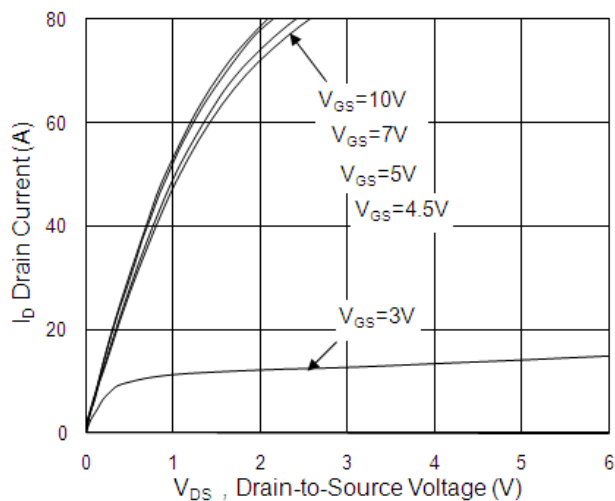


Fig.1 Typical Output Characteristics

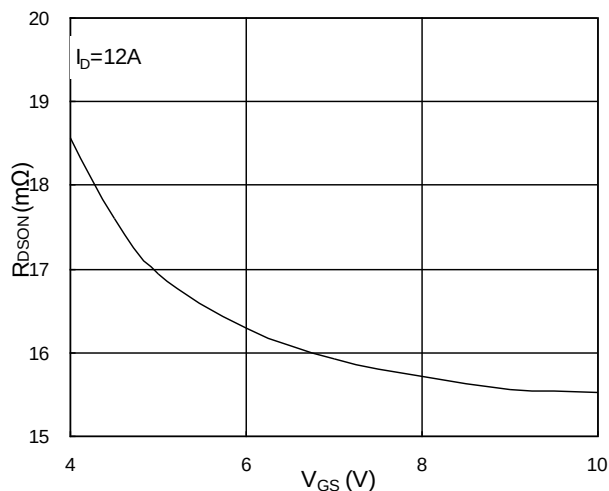


Fig.2 On-Resistance v.s Gate-Source

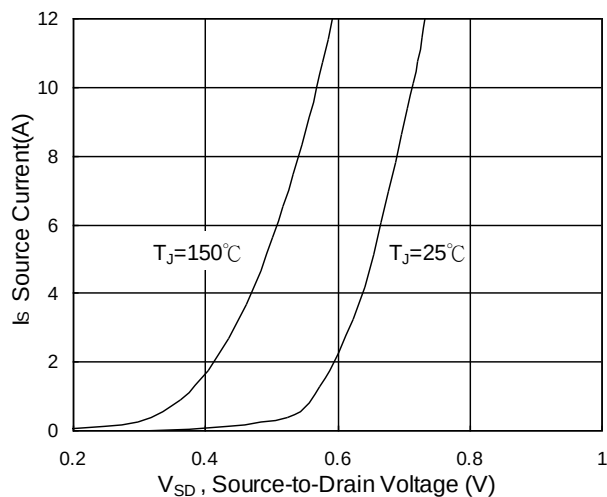


Fig.3 Forward Characteristics of Reverse

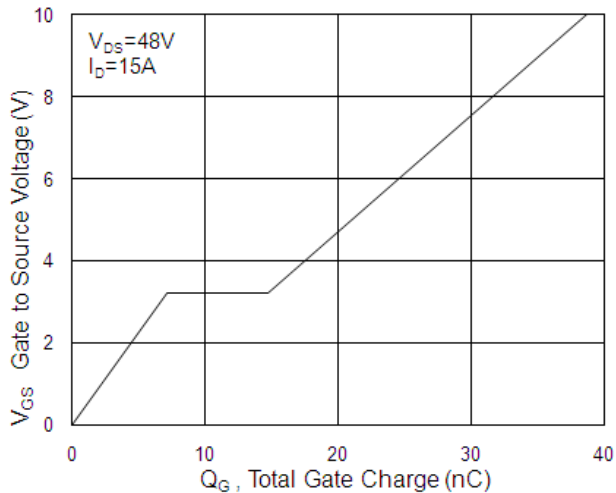


Fig.4 Gate-Charge Characteristics

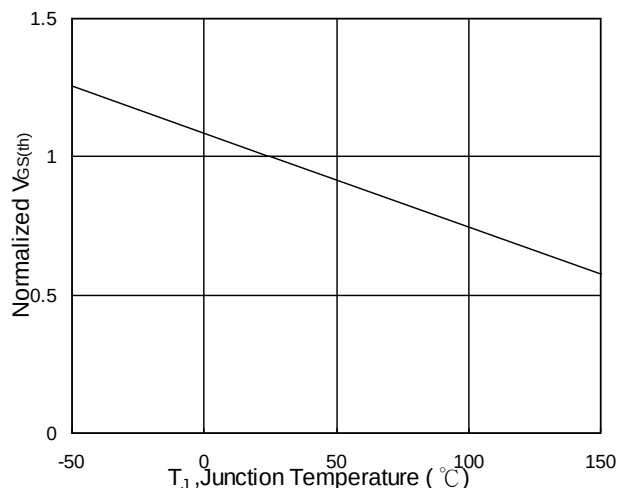


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

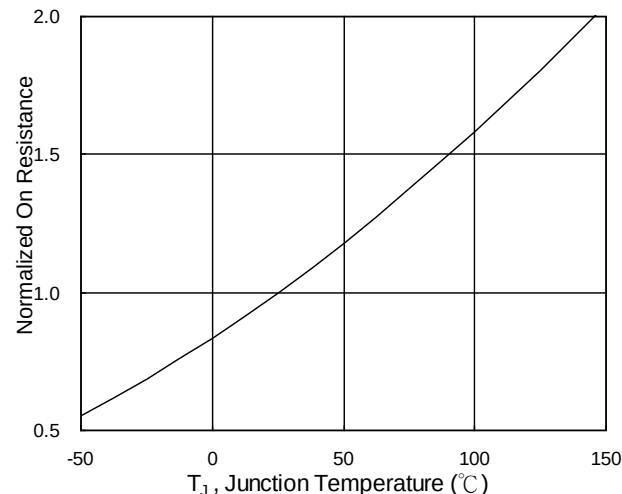


Fig.6 Normalized $R_{DS(on)}$ v.s T_J

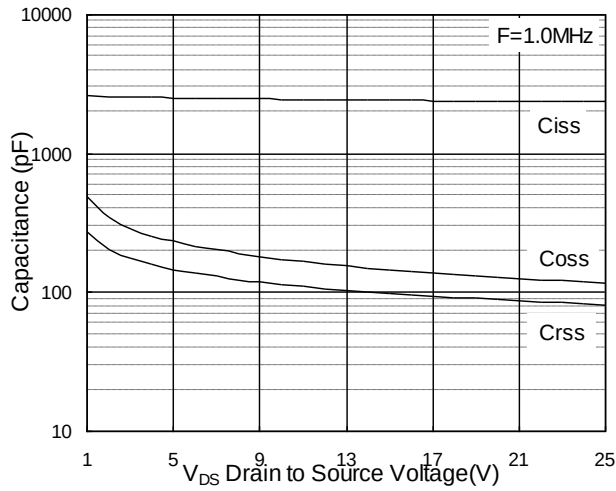


Fig.7 Capacitance

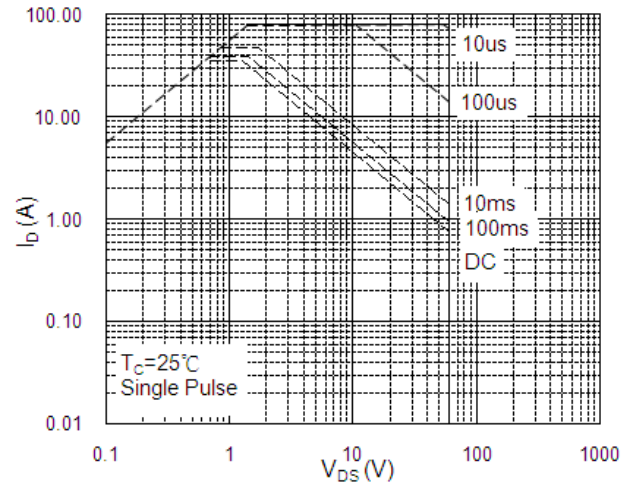


Fig.8 Safe Operating Area

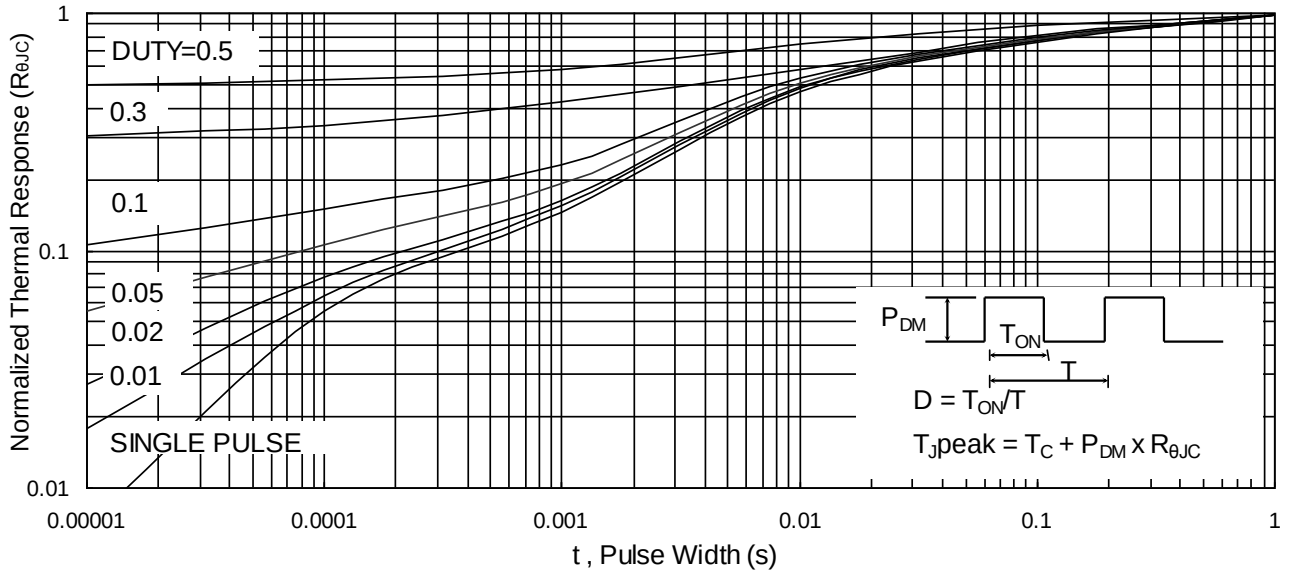


Fig.9 Normalized Maximum Transient Thermal Impedance

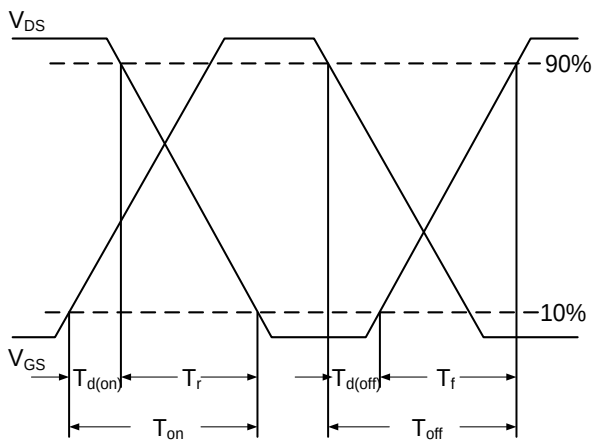


Fig.10 Switching Time Waveform

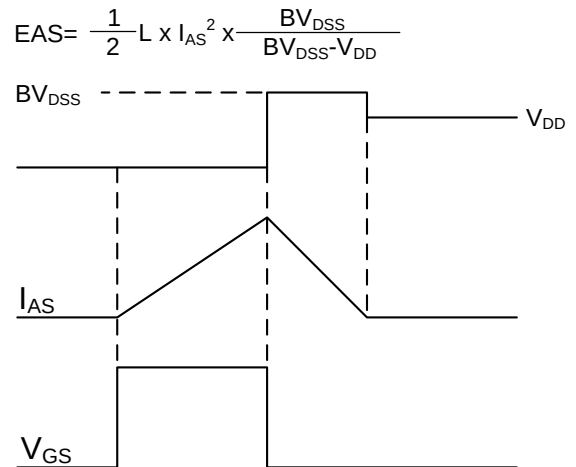
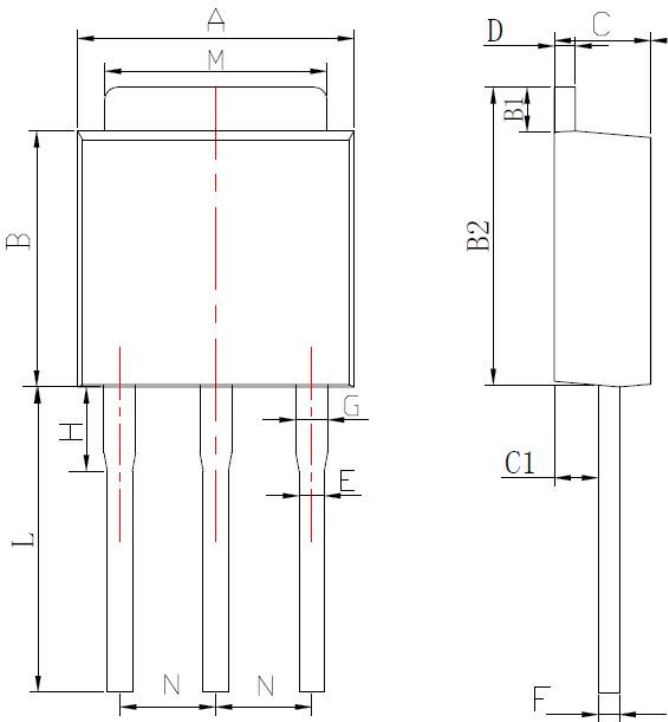


Fig.11 Unclamped Inductive Switching Waveform

Package Mechanical Data TO-251



Items	Values(mm)	
	MIN	MAX
A	6.30	6.90
B	5.20	6.30
B1	0.70	1.30
B2	6.80	7.40
C	2.10	2.50
C1	0.90	1.20
D	0.30	0.60
E	0.50	0.86
F	0.30	0.60
G	0.70	1.00
H	1.40	2.40
L*	9.00	9.80
M	5.10	5.50
N	2.09	2.49